- ★ Super Low Gate Charge
- ★ 100% EAS Guaranteed
- ★ Green Device Available
- ★ Excellent CdV/dt effect decline
- ★ Advanced high cell density Trench technology

Product Summary

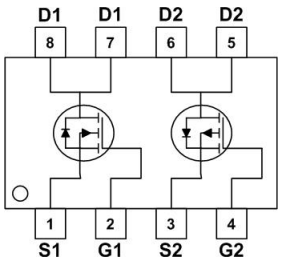
BVDSS	RDSON	ID
100V	70mΩ	10.0A
-100V	180mΩ	-5.0A

Description

The XR10G10S is the high performance complementary N-ch and P-ch MOSFETs with high cell density, which provide excellent RDSON and gate charge for most of the synchronous buck converter applications .

The XR10G10S meet the RoHS and Green Product requirement 100% EAS guaranteed with full function reliability approved.

SOP8 Pin Configuration



Absolute Maximum Ratings

Symbol	Parameter	Rating		Units
		N-Channel	P-Channel	
V_{DS}	Drain-Source Voltage	100	-100	V
V_{GS}	Gate-Source Voltage	±20	±20	V
I_D@T_A=25°C	Continuous Drain Current, V_{GS} @ 10V[1]	10.0	-5.0	A
I_D@T_A=70°C	Continuous Drain Current, V_{GS} @ 10V[1]	6.0	-3.5	A
I_{DM}	Pulsed Drain Current[2]	25	-9.5	A
EAS	Single Pulse Avalanche Energy[3]	22.5	35.3	mJ
I_{AS}	Avalanche Current	22.6	-26.6	A
P_D@T_A=25°C	Total Power Dissipation[4]	2.5	2.5	W
T_{STG}	Storage Temperature Range	-55 to 150	-55 to 150	°C
T_J	Operating Junction Temperature Range	-55 to 150	-55 to 150	°C

Thermal Data

Symbol	Parameter	Typ.	Max.	Unit
$R_{\theta JA}$	Thermal Resistance Junction-Ambient [1]	---	85	°C/W
$R_{\theta JC}$	Thermal Resistance Junction-Case[1]	---	62.5	°C/W

Electrical Characteristics（T_J = 25°C, unless otherwise noted）

Parameter		Symbol	Test Conditions	Min.	Typ.	Max.	Unit
Static Characteristics							
Drain-Source Breakdown Voltage		$V_{(BR)DSS}$	V_{GS} = 0V, I_D = 250μA	100	-	-	V
Gate-body Leakage current		I_{GSS}	V_{DS} = 0V, V_{GS} = ±20V	-	-	±100	nA
Zero Gate Voltage Drain Current	T_J=25°C	I_{DSS}	V_{DS} =100V, V_{GS} = 0V	-	-	1	μA
	T_J=100°C			-	-	100	
Gate-Threshold Voltage		$V_{GS(th)}$	V_{DS} = V_{GS}, I_D = 250μA	1.2	-	2.5	V
Drain-Source on-Resistance[4]		$R_{DS(on)}$	V_{GS} = 10V, I_D = 5A	-	70	90	mΩ
			V_{GS} = 4.5V, I_D = 3A	-	75	105	
Forward Transconductance[4]		g_{fs}	V_{DS}=5V , I_D=5A	-	12	-	S
Dynamic Characteristics[5]							
Input Capacitance		C_{iss}	V_{DS} = 15V, V_{GS} =0V, f =1MHz	-	1220	-	pF
Output Capacitance		C_{oss}		-	53	-	
Reverse Transfer Capacitance		C_{rss}		-	42	-	
Gate Resistance		R_g	f =1MHz	-	1.3	-	Ω
Switching Characteristics[5]							
Total Gate Charge		Q_g	V_{GS} = 10V, V_{DS} = 50V, I_D=5A	-	20.6	-	nC
Gate-Source Charge		Q_{gs}		-	4	-	
Gate-Drain Charge		Q_{gd}		-	3.7	-	
Turn-On Delay Time		$t_{d(on)}$	V_{GS} =10V, V_{DD} =50V, R_G = 3Ω, I_D= 5A	-	4.7	-	ns
Rise Time		t_r		-	21	-	
Turn-Off Delay Time		$t_{d(off)}$		-	20	-	
Fall Time		t_f		-	16	-	
Drain-Source Body Diode Characteristics							
Diode Forward Voltage[4]		V_{SD}	I_S = 1A, V_{GS} = 0V	-	-	1.2	V
Continuous Source Current	T_C=25°C	I_S	-	-	-	10	A

Notes:

1. Repetitive rating, pulse width limited by junction temperature $T_{J(MAX)}$=150°C.

2.The data tested by pulsed , pulse width ≤ 300us , duty cycle ≤ 2%

3.The EAS data shows Max. rating . The test condition is V_{DD}=25V,V_{GS}=10V,L=0.1mH,I_{AS}=8A

4.The power dissipation is limited by 150°C junction temperature

5.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

P-Channel Electrical Characteristics (T_J=25 ℃, unless otherwise noted)

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
BV_{DSS}	Drain-Source Breakdown Voltage	V_{GS}=0V , I_D=-250uA	-100	---	---	V
$R_{DS(ON)}$	Static Drain-Source On-Resistance[2]	V_{GS}=-10V , I_D=-3A	---	180	220	mΩ
		V_{GS}=-4.5V , I_D=-2A	---	210	255	
$V_{GS(th)}$	Gate Threshold Voltage	V_{GS}=V_{DS} , I_D =-250uA	-1.2	---	-2.5	V
I_{DSS}	Drain-Source Leakage Current	V_{DS}=-80V , V_{GS}=0V , T_J=25℃	---	---	-1	uA
		V_{DS}=-80V , V_{GS}=0V , T_J=85℃	---	---	-30	
I_{GSS}	Gate-Source Leakage Current	V_{GS}=±20V , V_{DS}=0V	---	---	±100	nA
R_g	Gate Resistance	V_{DS}=0V , V_{GS}=0V , f=1MHz	---	13	---	Ω
Q_g	Total Gate Charge (-10V)	V_{DS}=-50V , V_{GS}=-10V , I_D=-2A	---	19	---	nC
Q_{gs}	Gate-Source Charge		---	3.4	---	
Q_{gd}	Gate-Drain Charge		---	2.9	---	
$T_{d(on)}$	Turn-On Delay Time	V_{DD}=-30V , V_{GS}=-10V , R_G=3.3Ω, I_D=-1A	---	9	---	ns
T_r	Rise Time		---	6	---	
$T_{d(off)}$	Turn-Off Delay Time		---	39	---	
T_f	Fall Time		---	33	---	
C_{iss}	Input Capacitance	V_{DS}=-30V , V_{GS}=0V , f=1MHz	---	1228	---	pF
C_{oss}	Output Capacitance		---	41	---	
C_{rss}	Reverse Transfer Capacitance		---	29	---	

Diode Characteristics

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
I_S	Continuous Source Current[1,5]	V_G=V_D=0V , Force Current	---	---	-5.0	A
V_{SD}	Diode Forward Voltage[2]	V_{GS}=0V , I_S=-1A , T_J=25℃	---	---	-1.2	V

Note :
1.The data tested by surface mounted on a 1 inch^2 FR-4 board with 2OZ copper.
2.The data tested by pulsed , pulse width ≦ 300us , duty cycle ≦ 2%
3.The EAS data shows Max. rating . The test condition is V_{DD}=-25V,V_{GS}=-10V,L=0.5mH,I_{AS}=-14A
4.The power dissipation is limited by 150℃ junction temperature
5.The data is theoretically the same as I_D and I_{DM} , in real applications , should be limited by total power dissipation.

N-Channel Typical Characteristics

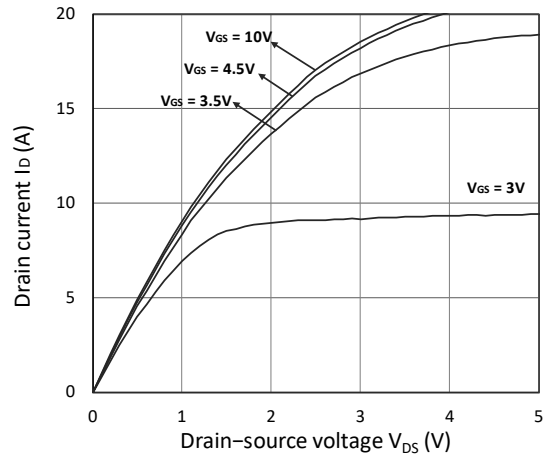


Figure 1. Output Characteristics

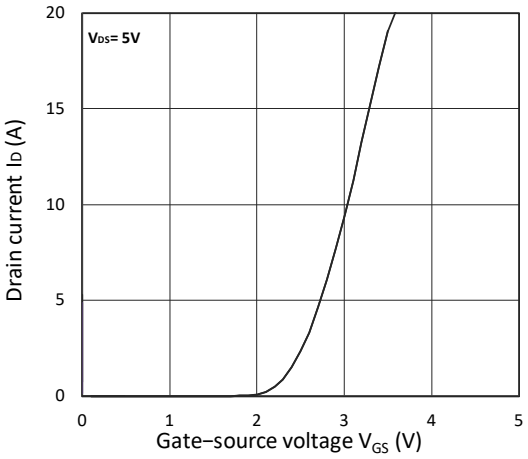


Figure 2. Transfer Characteristics

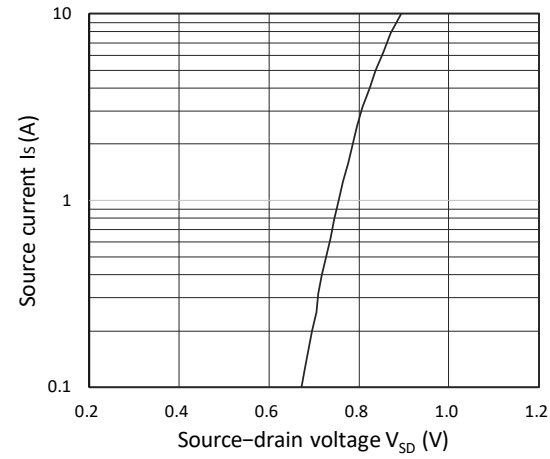


Figure 3. Forward Characteristics of Reverse

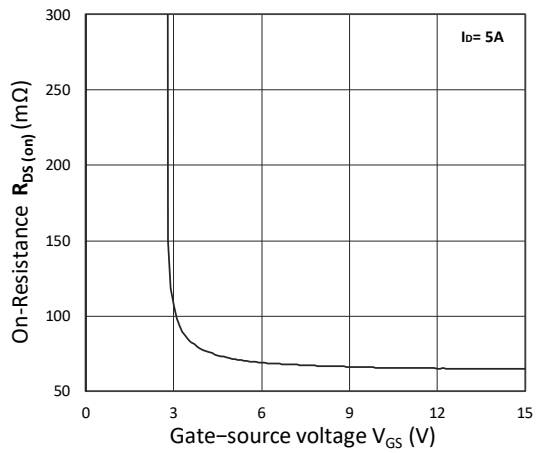


Figure 4. $R_{DS(ON)}$ vs. V_{GS}

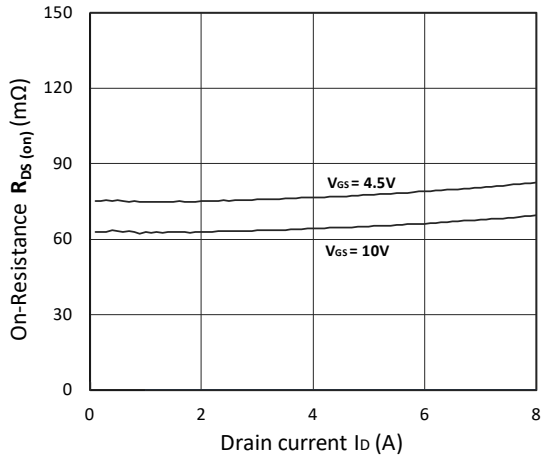


Figure 5. $R_{DS(ON)}$ vs. I_D

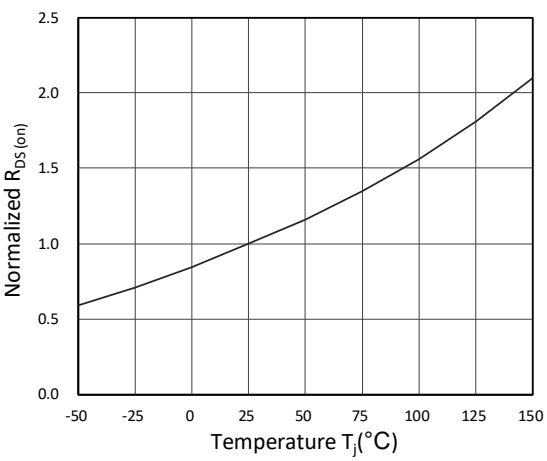


Figure 6. Normalized $R_{DS(on)}$ vs. Temperature

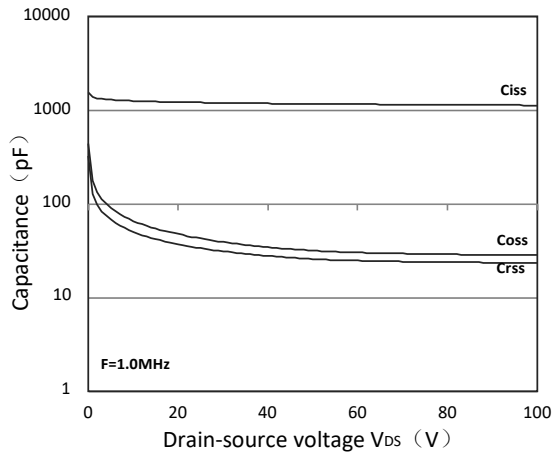


Figure 7. Capacitance Characteristics

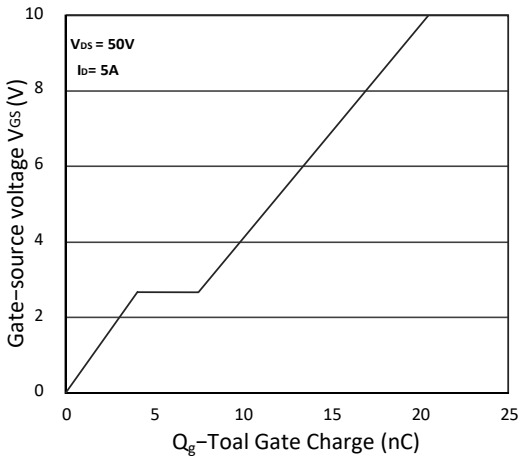


Figure 8. Gate Charge Characteristics

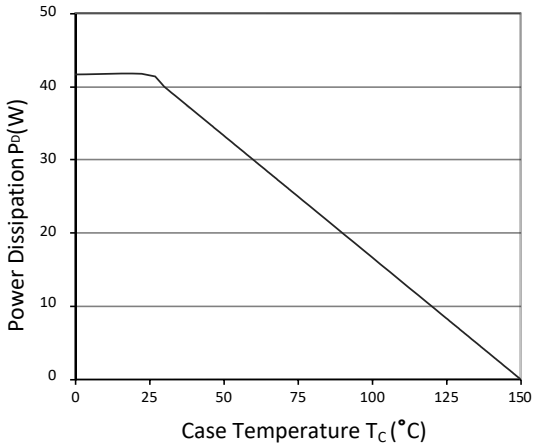


Figure 9. Power Dissipation

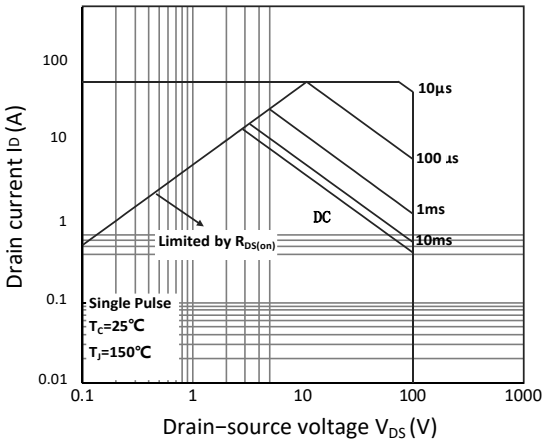


Figure10. Safe Operating Area

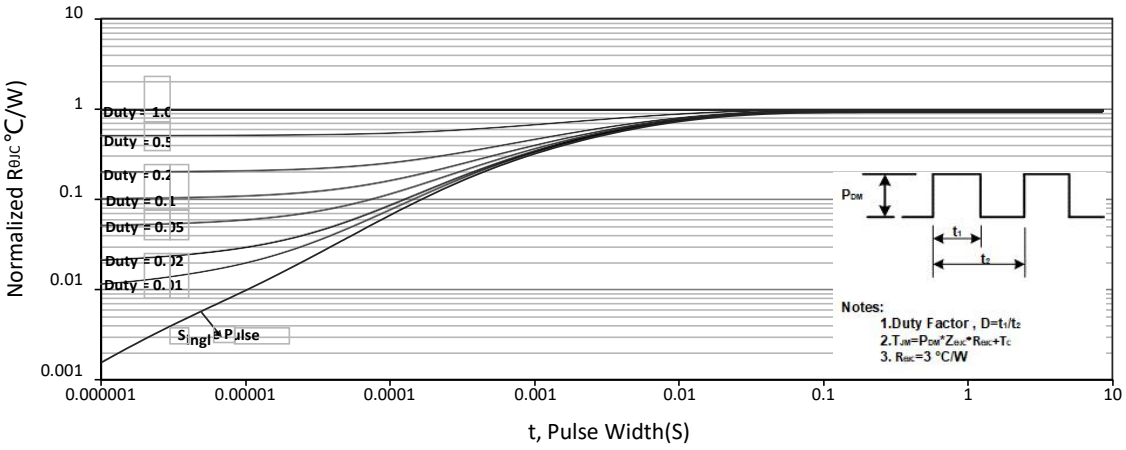


Figure 11. Normalized Maximum Transient Thermal Impedance

P-Channel Typical Characteristics

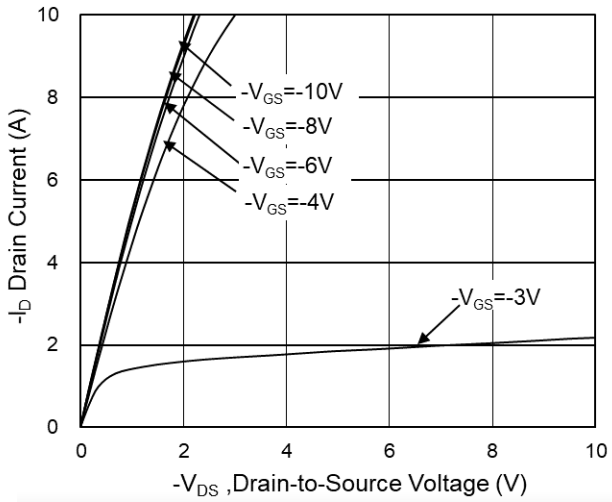


Fig.1 Typical Output Characteristics

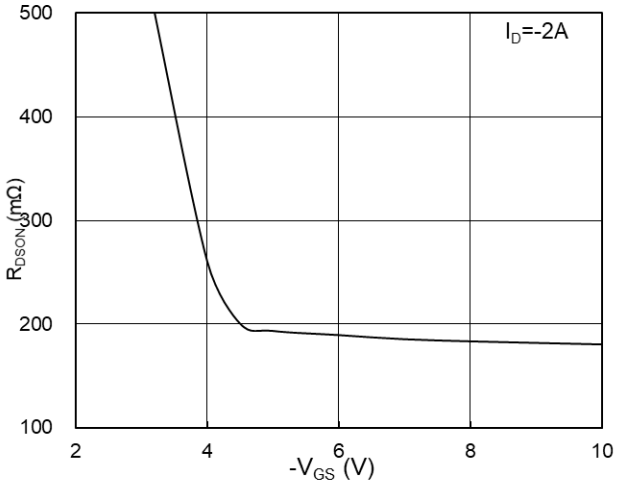


Fig.2 On-Resistance vs G-S Voltage

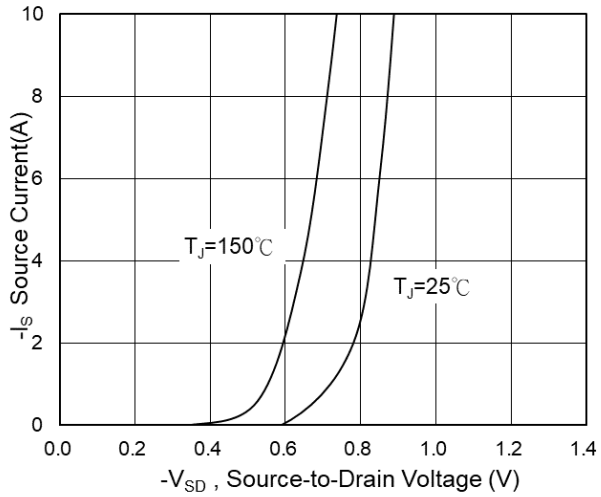


Fig.3 Source Drain Forward Characteristics

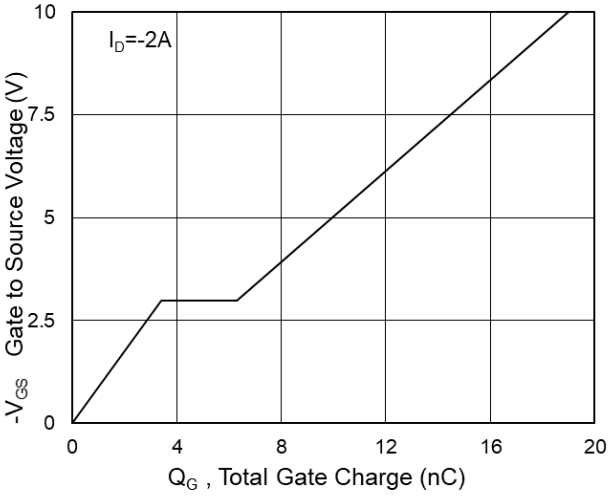


Fig.4 Gate-Charge Characteristics

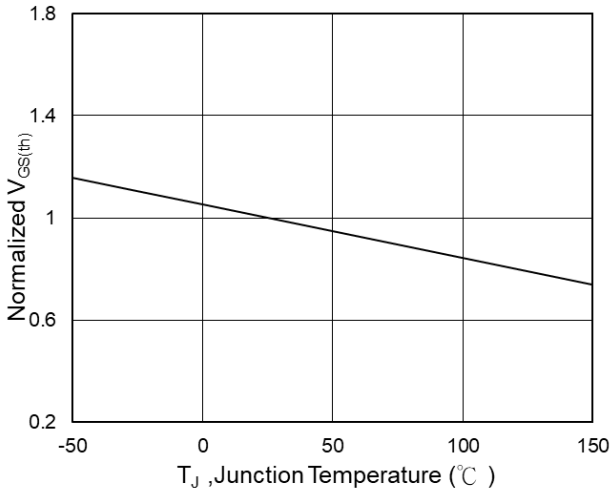


Fig.5 Normalized $V_{GS(th)}$ vs T_J

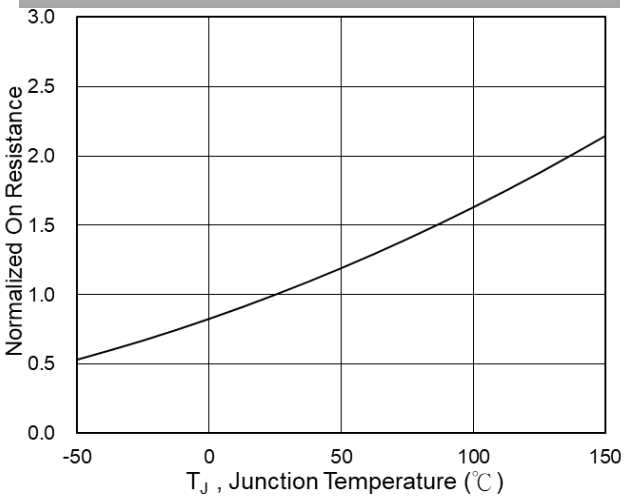


Fig.6 Normalized R_{DSON} vs T_J

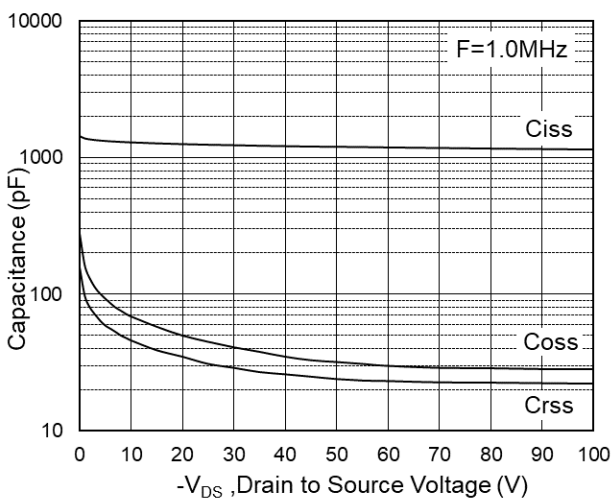


Fig.7 Capacitance

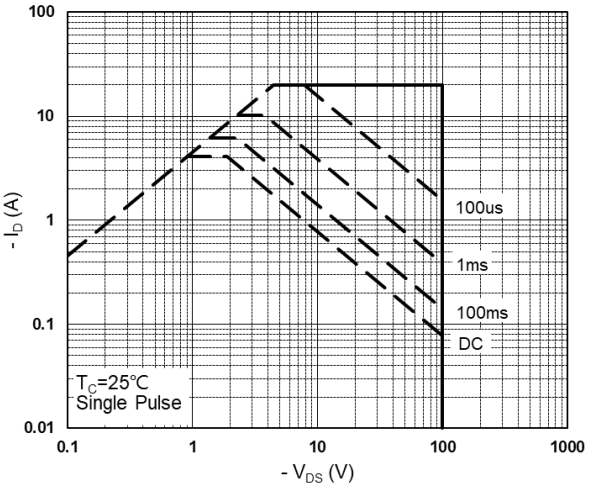


Fig.8 Safe Operating Area

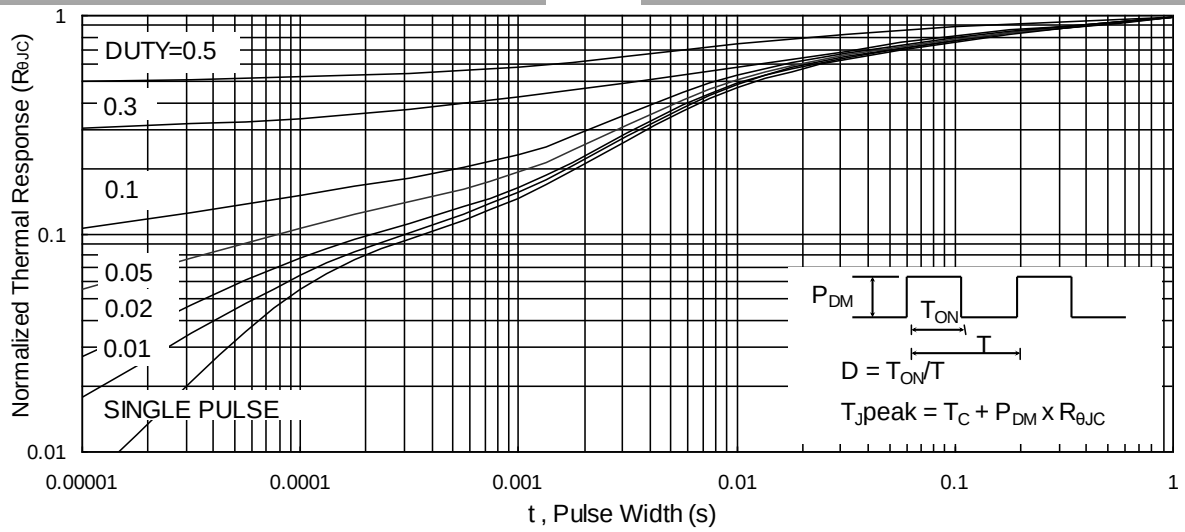


Fig.9 Normalized Maximum Transient Thermal Impedance

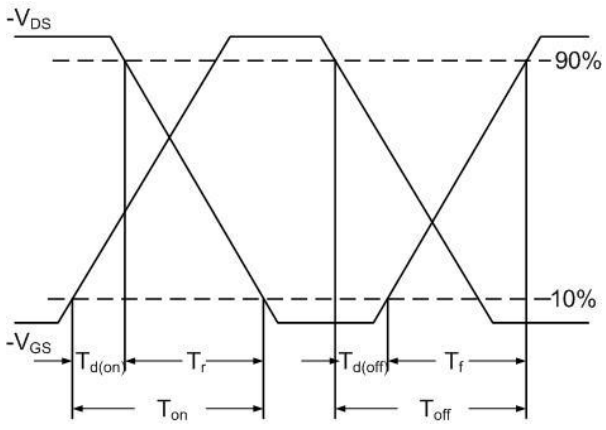


Fig.10 Switching Time Waveform

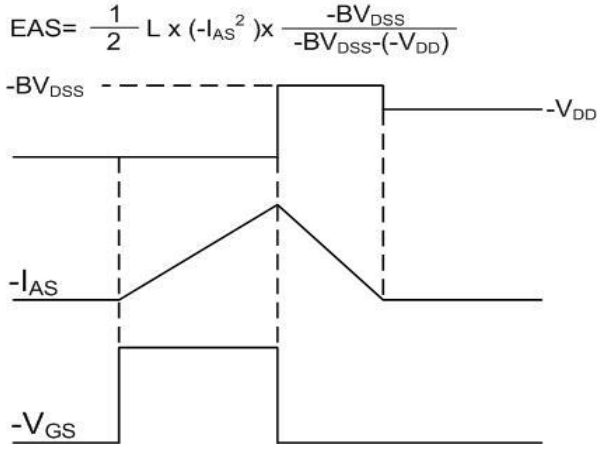
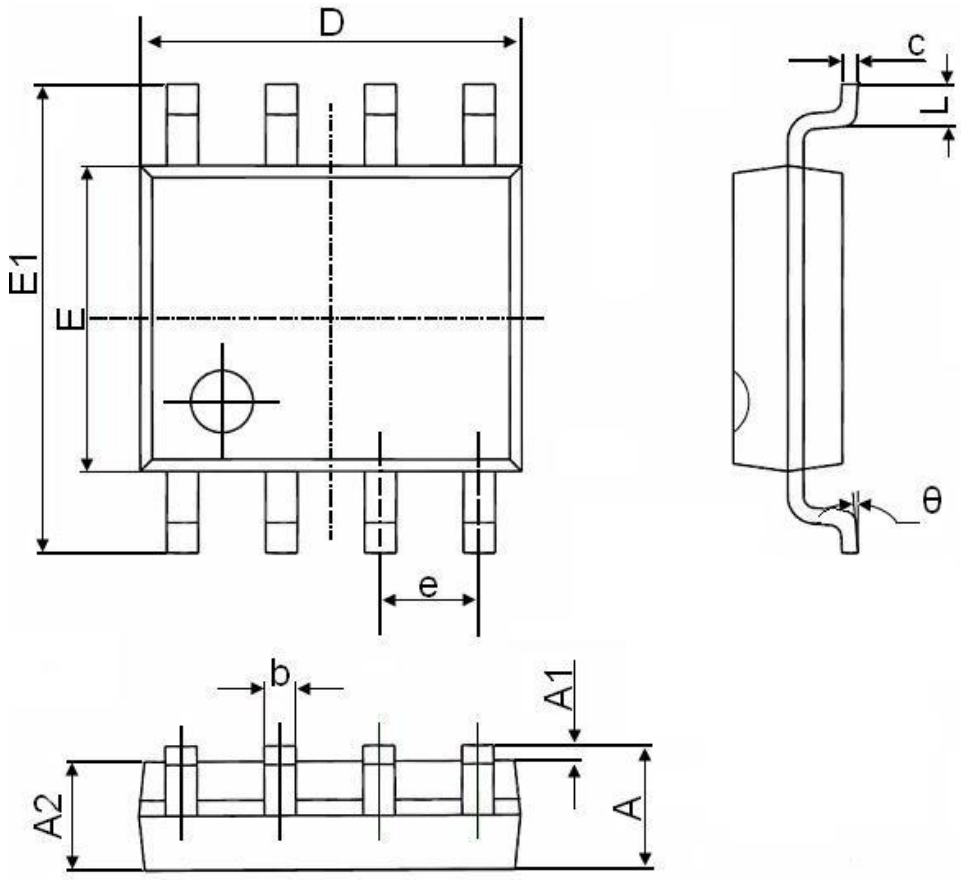


Fig.11 Unclamped Inductive Waveform

SOP-8 Package Information



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min.	Max.	Min.	Max.
A	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.006	0.010
D	4.700	5.100	0.185	0.200
E	3.800	4.000	0.150	0.157
E1	5.800	6.200	0.228	0.244
e	1.270(BSC)		0.050(BSC)	
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°